

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A microencapsulated adhesive component, comprising:

a cross-linking constituent microencapsulated with a silanized polybutadiene, wherein ~~the reactive constituent has been first reacted in the melt with cross-linking, thereby resulting in a cross-linkable hot-melt adhesive component for coating and/or laminating surface formations.~~

Claim 2 (Original): The microencapsulated adhesive component as claimed in Claim 1, wherein the cross-linking constituent is micro-encapsulated with a silanized polybutadiene in a ratio of 4:1.

Claim 3 (Original): The microencapsulated adhesive component as claimed in Claim 1, wherein the silanized polybutadiene has a silicon content of 2 to 10% by weight, a molecular weight of 1500 to 2500 g/mol and a viscosity of 1000 to 3000 mPas.

Claim 4 (Original): The microencapsulated adhesive component as claimed in Claim 1, wherein the cross-linking constituent is an isocyanate compound which has more than two reactive groups per molecule.

Claim 5 (Currently Amended): The microencapsulated adhesive component as claimed in Claim ~~[[1]]~~ 4, wherein the isocyanate compound has a melting range of 110 to 130°C.

Claim 6 (Currently Amended): The microencapsulated adhesive component as claimed in Claim 1, wherein the cross-linking constituent is an isocyanate which ~~is micro-encapsulated with a silanized polybutadiene and which reacts~~ is reactive with a second constituent which is a copolyamide or copolyester.

Claim 7 (Currently Amended): The microencapsulated adhesive component as claimed in Claim 6, wherein the second constituent is an ~~amine-regulated~~ amine-terminated copolyamide with a melting range of 90 to 150°C and a solution viscosity or relative melting viscosity η/c in the range of 1.2 to 1.7.

Claim 8 (Currently Amended): The ~~process~~ microencapsulated adhesive component as claimed in Claim 6, wherein the second constituent is an OH group terminated copolyester prepared from terephthalic acid, isophthalic acid and butanediol or butanediol in combination with small quantities of up to 12 mole % of another diol, having a melting point of 100 to 150°C.

Claim 9 (Currently Amended): An aqueous printing paste, comprising:
the microencapsulated ~~cross-linking constituent~~ adhesive component of Claim 1 dispersed in an aqueous paste.

Claim 10 (Original): The printing paste according to Claim 9, wherein the paste further comprises an acid catalyst, a commercial surfactant, a defoaming agent, a thickener and water.

Claim 11 (Currently Amended): The ~~printing paste~~ method according to Claim ~~10~~ 19, wherein the aqueous paste is applied to a substrate by rotary screen printing.

Claim 12 (Currently Amended): An aqueous adhesive printing paste, comprising:
the microencapsulated ~~cross-linking constituent~~ adhesive component of Claim 1 combined with a second constituent of a copolyamide or a copolyester dispersed in an aqueous paste.

Claim 13 (Currently Amended): A method of bonding surfaces, comprising:
applying the paste of Claim ~~[[9]]~~ 18 onto a surface as the base dots of double dot technology as a strike back barrier;
applying, as the upper dot component of the double dot process, an amine ~~regulated~~ terminated copolyamide; and
effecting bonding between the materials of the applied dots.

Claim 14 (Currently Amended): A process, comprising:
micro-encapsulating a cross-linking constituent in a silanized polybutadiene, ~~thereby resulting in a cross-linkable hot-melt adhesive component for coating and/or laminating surface formations.~~

Claim 15 (New): The aqueous adhesive printing paste of Claim 12, wherein the cross-linking constituent is an isocyanate compound.

Claim 16 (New): The aqueous adhesive printing paste of Claim 15, wherein the second constituent is an amine-terminated copolyamide with a melting range of 90 to 150°C and a solution viscosity or relative melting viscosity η/c in the range of 1.2 to 1.7.

Claim 17 (New): The aqueous adhesive printing paste of Claim 15, wherein the second constituent is an OH group terminated copolyester prepared from terephthalic acid, isophthalic acid and butanediol or butanediol in combination with small quantities of up to 12 mole % of another diol, having a melting point of 100 to 150°C.

Claim 18 (New): The aqueous printing paste of Claim 9, wherein the cross-linking constituent is an isocyanate.

Claim 19 (New): A method comprising applying the aqueous printing paste of Claim 15 to a substrate.

DISCUSSION OF THE AMENDMENT

Claim 1 has been amended by, in effect, deleting functional language. Claim 5 has been amended to depend on Claim 4. Claim 6 has been amended by deleting superfluous language and to recite that the isocyanate is *reactive* with the second constituent, thereby reciting a function of the isocyanate, and to clarify that the claim does not require that the second constituent be part of the microencapsulated adhesive component. Claim 7 has been amended by replacing the term "regulated" with the more accurate --terminated--, as supported in the specification at page 5, line 23. Claim 8 has been amended to correct an obvious error, since Claim 6 is not drawn to a process. Claim 9 has been amended for antecedent basis purposes. Claim 11 has been amended to depend on new Claim 19, discussed *infra*, as supported in the specification at page 4, lines 25-26 and Example 2. Claim 12 has been amended for antecedent basis purposes. Claim 13 has been amended to depend on new Claim 18, discussed *infra*, and by replacing the term "regulated" with the more accurate --terminated--, supported as discussed above. Claim 14 has been amended by deleting functional language.

New Claims 15-19 have been added. Claim 15 is analogous to Claim 6, but depends on Claim 12, thereby claiming the combination of the microencapsulated adhesive component and the second constituent. Claims 16 and 17 depend on Claim 15, and correspond to Claims 7 and 8, respectively. Claim 18 is supported, for example, in the specification at page 4, line 9 ff. Claim 19 is supported in the specification at page 4, line 19 ff and Example 2.

No new matter has been added by the above amendment. Claims 1-19 are now pending in the application.